



# 100% Material Declaration Data Sheet PC84

PK160 (v1.2) October 5, 2006

Material Declaration Data Sheet

**Average Weight: 7.248 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					<b>0.02369</b>	<b>0.33%</b>
	Silicon	7440-21-3	100.00		0.023688	
Die Attach Material					<b>0.00377</b>	<b>0.05%</b>
	Resin	Trade Secret	7.00		0.000264	
	Silver	7440-22-4	70.00		0.002640	
	Zirconium	Trade Secret	0.10		0.001252	
	Mixed aryl allyl glycidyl compounds	Trade Secret	3.00		0.000113	
	Amine	Trade Secret	5.00		0.000189	
	Gamma Butyrolactone	Trade Secret	5.00		0.000189	
	Diglycidylether of bisphenol-F	Trade Secret	10.00		0.000377	
Mold Compound					<b>5.91943</b>	<b>81.67%</b>
	Epoxy Resin (EP)	Trade Secret	7.50		0.443957	
	Silica	60676-86-0	86.00		5.090706	
	Carbon Black	1333-86-4	0.50		0.029597	
	Epoxy Cresol Novolac	Trade Secret	2.00		0.118389	
	Phenolic Resin	Trade Secret	4.00		0.23677	
Leadframe					<b>1.25241</b>	<b>17.28%</b>
	Copper	7440-50-8	99.90		1.251153	
	Zirconium	7440-67-7	0.10		0.001252	
Leadframe Plating					<b>0.00254</b>	<b>0.04%</b>
	Silver	7440-22-4	100.00		0.002544	
Bond Wire					<b>0.00348</b>	<b>0.05%</b>
	Gold	7440-57-5	100.00		0.00348	
Ext. Plating					<b>0.04241</b>	<b>0.58%</b>
	Tin	7440-31-5	85.00		0.0360485	
	Lead	7439-92-1	15.00		0.0063615	

PK160 (v1.2) October 5, 2006

[www.xilinx.com](http://www.xilinx.com)

1

## Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/08/06	1.0	Initial release.
7/12/06	1.1	100% Material Declaration.
10/5/06	1.2	Updated component descriptions.